

### REMARKS

The present application has been amended in response to the Examiner's Office Action to place the application in condition for allowance. Applicant, by the amendments presented above, has made a concerted effort to present claims which clearly define over the prior art of record, and thus to place this case in condition for allowance.

In the Office Action, the Examiner rejected claims 1-21 under 35 U.S.C. §112 due to claim 1 containing the phrase "regarding whether the product is used or not." Claim 1 has been amended such that it no longer contains this phrase. As such, Applicant respectfully requests that the rejection under 35 U.S.C. §112 be withdrawn.

The Examiner also rejected claims 1-2 and 5-21 under 35 U.S.C. §102(b) as being anticipated by United States Patent No. 5,864,394 (Jordan, III et al.), or in the alternative, under 35 U.S.C. §103(a) as being obvious over a combination of Jordan, III et al. in view of an article authored by Abugov et al. Claim 1 has been amended, and Applicant respectfully submits that claim 1, and those claims which depend therefrom, are allowable.

While claim 1 has been amended to distinguish even further away from, for example, Jordan, III et al., Applicant respectfully submits that Jordan, III et al. is very different from the present invention. Jordan, III et al. deals with scanning for anomalies. That is not what the present invention is directed to. In contrast, the present invention is directed to calculating high-resolution wafer parameter profiles.

Notwithstanding this, claim 1 has been amended to further distinguish the claimed invention from that which is disclosed in Jordan, III et al. Claim 1 now specifically claims the step of defining an appropriate product/device input dataset for a plurality of different die sizes and products, wherein the dataset comprises information relating to the size of each die in two directions as well as the location of at least one of the corners of each die. This is neither disclosed nor suggested by the cited references.

Additionally, claim 1 has been amended to specifically claim collecting a die level yield bin dataset for one of the products/devices defined in the previous step. This also is neither disclosed nor suggested by the cited references.

In view of the above amendments and remarks, Applicant respectfully submits that the claims of the application are allowable over the rejections of the Examiner. Should the present claims not be deemed adequate to effectively define the patentable subject matter, the Examiner is respectfully urged to call the undersigned attorney of record to discuss the claims in an effort to reach an agreement toward allowance of the present application.

Respectfully submitted,

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